SN74CBTK6800 10-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS AND ACTIVE-CLAMP UNDERSHOOT-PROTECTION CIRCUIT

SCDS107B - APRIL 2000 - REVISED OCTOBER 2000

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Power Off Disables Outputs, Permitting Live Insertion
- Outputs Are Precharged by Bias Voltage to Minimize Signal Distortion During Live Insertion
- Active-Clamp Undershoot-Protection
 Circuit on the I/Os Clamps Undershoots
 Down to -2 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

(TOP VIEW) 24 V_{CC} \overline{ON} Α1 23 B1 22 B2 A2 3 А3 4 21 B3 A4 20 B4 19 B5 A5 A6 7 18 **∏** B6 A7 17 **∏** B7 16 B8 8A 15 **∏** B9 Α9 10 A10 Π 11 14 B10 13 BIASV **GND** 12

DBQ, DGV, DW, OR PW PACKAGE

description

The SN74CBTK6800 device provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows bidirectional connections to be made while adding near-zero propagation delay. The device also precharges the B port to a user-selectable bias voltage (BIASV) to minimize live-insertion noise.

The A and B ports have an active-clamp undershoot-protection circuit. When there is an undershoot, the active-clamp circuit is enabled and current from V_{CC} is supplied to clamp the output, preventing the pass transistor from turning on.

The SN74CBTK6800 is organized as one 10-bit switch with a single enable (\overline{ON}) input. When \overline{ON} is low, the switch is on, and port A is connected to port B. When \overline{ON} is high, the switch between port A and port B is open. When \overline{ON} is high or V_{CC} is 0 V, B port is precharged to BIASV through the equivalent of a 10-k Ω resistor.

ORDERING INFORMATION

TA	PACKAGE†		PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - DW		Tube		SN74CBTK6800DW	CBTK6800
	30IC - DW	Tape and reel	SN74CBTK6800DWR	CBTK0000		
–40°C to 85°C	SSOP (QSOP) – DBQ	Tape and reel	SN74CBTK6800DBQR	CBTK6800		
	TSSOP – PW	Tape and reel	SN74CBTK6800PWR	BK6800		
	TVSOP - DGV	Tape and reel	SN74CBTK6800DGVR	BK6800		

T Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUT ON	FUNCTION
L	A port = B port
н	A port = Z B port = BIASV

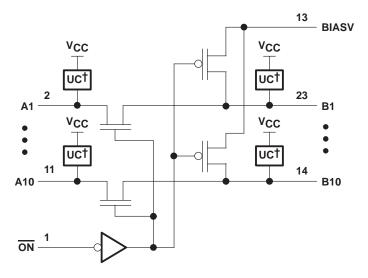


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SCDS107B - APRIL 2000 - REVISED OCTOBER 2000

logic diagram (positive logic)



[†] Undershoot clamp

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}		−0.5 V to 7 V
Bias voltage range, BIASV		−0.5 V to 7 V
Input voltage range, V _I (see Note 1)		−0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I _{IK} (V _I < 0)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DBQ package	61°C/W
	DGV package	86°C/W
	DW package	46°C/W
	PW package	88°C/W
Storage temperature range, T _{sto}	· · · · · · · · · · · · · · · · · · ·	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
BIASV	Supply voltage	1.3	VCC	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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SCDS107B - APRIL 2000 - REVISED OCTOBER 2000

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIO	NS	MIN	TYP†	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V
VIKU		$V_{CC} = 5.5 \text{ V},$	$0~mA \geq I_{I} \geq -50~mA,$	OE = 5.5 V			-2	V
II		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±5	μΑ
l _{off}		$V_{CC} = 0$,	V_{I} or $V_{O} = 0$ to 5.5 V,	BIASV = Open			20	μΑ
lo		$V_{CC} = 4.5 \text{ V},$	V _O = 0,	BIASV = 2.4 V	0.25			mA
Icc		$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or GND,	I _O = 0			20	μΑ
Δl _{CC} ‡	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
Ci	Control inputs	V _I = 3 V or 0				3		pF
C _{o(OFF}	·)	$V_0 = 3 \text{ V or } 0,$	Switch off			8.5		pF
		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA		11	20	
ron§			V. = 0	I _I = 64 mA		3	7	Ω
		V _{CC} = 4.5 V	V _I = 0	I _I = 30 mA		3	7	
			V _I = 2.4 V,	I _I = 15 mA		6	15	

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	1 ± 0.5 V		= 5 V 5 V	UNIT
	(IIVI O1)	(001101)		MIN MAX	MIN	MAX	
t _{pd} ¶	A or B	B or A		0.35	5	0.25	ns
^t PZH		A or B	BIASV = GND	(3 2	5.1	ns
tPZL	ON	AUIB	BIASV = 3 V	(3 2	5.6	115
t _{PHZ}	ŌN	A or B	BIASV = GND	5.5	5 1	5	ns
t _{PLZ}		AUIB	BIASV = 3 V	5.5	5 2	5.9	115

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[†] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25$ °C. ‡ This is the increase in supply current for each input that is at the specified TTL-voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

undershoot characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Voutu	See Figures 1 and 2, and Table 1	2	V _{OH} -0.3		V

[†] All typical values are at $V_{CC} = 5 \text{ V}$ (unless otherwise noted), $T_A = 25^{\circ}C$.

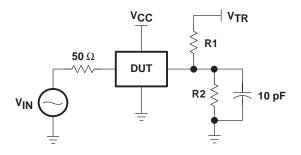


Figure 1. Device Test Setup

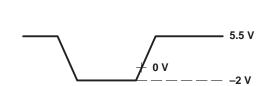


Figure 2. Transient Input Voltage Waveform

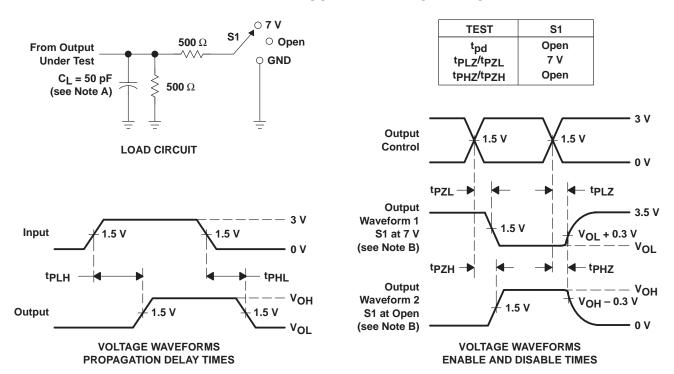
Table 1. Device Test Conditions

PARAMETER	VALUE	UNIT
B port under test‡	See Figure 1	
VIN	See Figure 2	V
t _W	20	ns
t _r	2	ns
t _f	2	ns
R1 = R2	100	kΩ
V_{TR}	11	V
V _{CC}	5.5	V
BIASV	Open	

[‡] Other B-port outputs are open.

SCDS107B - APRIL 2000 - REVISED OCTOBER 2000

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{r} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as t_{dis}.
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms

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